

# 電子材料向け多核フェノール

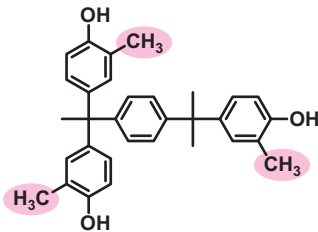
開発品

Polyphenol for electronic materials

電子材料用途を志向した多様な骨格の多核フェノールを開発しています。

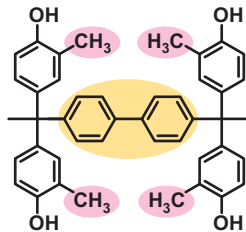
We develop polyphenol with diverse structures for electronic materials.

## 製品 Products



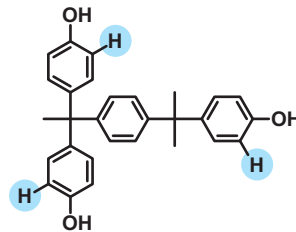
TrisOC-PA

開発品



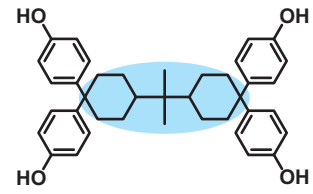
TekOC-DABP

開発品



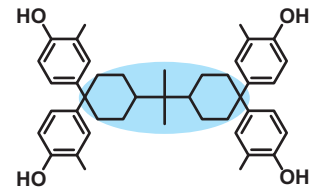
TrisP-PA

既存品



TekP-4HBPA

既存品



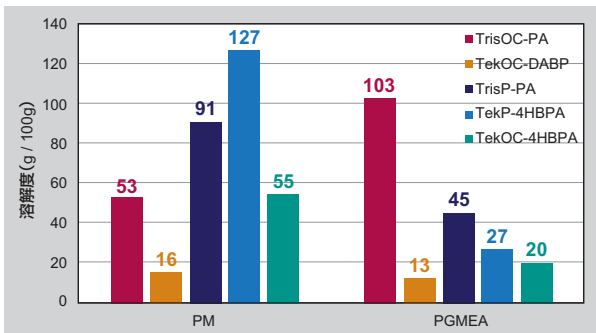
TekOC-4HBPA

既存品

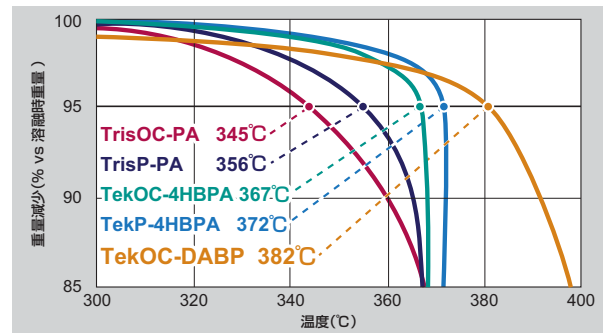
- メチル基  $-CH_3$  導入による高溶解性・高安定性  
Introducing methyl groups results in high solubility and stability.
- 剛直なビフェニル骨格 導入による高耐熱性  
Introducing biphenyl moiety results in high heat resistant.

## 物性 Properties

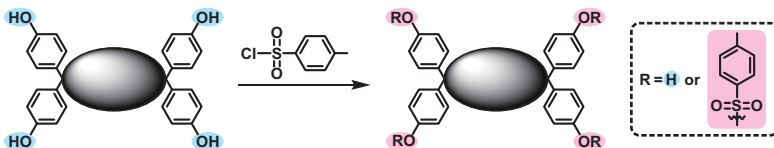
### ●溶解性 Solubility



### ●耐熱性 Heat resistant



### ●スルホニルエステル溶解性 Solubility of sulfonyl esters



#### Test conditions

Each sulfonyl ester was filtered after dissolving in PM or PGMEA. The resulting solution was stored for 14 days under  $-18^{\circ}\text{C}$ . After storage, we checked the presence of precipitation.

Polyphenols	TrisOC-PA	TekOC-DABP	TrisP-PA	TekP-4HBPA	TekOC-4HBPA
Ester conv. rate	88%	83%	89%	81%	81%
Test conc.	Results of dissolution test (PM / PGMEA)				
10%	○ / ○	× / ○	× / ○	○ / ○	○ / ○
25%	○ / ○	× / ○	× / ×	○ / ○	○ / ○
40%	○ / ○	× / ○	× / ×	○ / ○	○ / ○

○: 析出なし good miscibility even at  $-18^{\circ}\text{C}$  ×: 析出あり observed precipitation